

Title (en)  
Floor covering board, connection element and floor covering, and method of producing a floor covering

Title (de)  
Bodenbelagsplatte, Verbindungselement und Bodenbelag, sowie Herstellungsverfahren eines Bodenbelags

Title (fr)  
Plaque de revêtement de sol, élément de liaison et revêtement de sol, ainsi que procédé de fabrication d'un revêtement de sol

Publication  
**EP 2374932 A3 20131218 (DE)**

Application  
**EP 11002925 A 20110407**

Priority  
DE 102010014131 A 20100407

Abstract (en)  
[origin: EP2374932A2] The board (10) has a lower side, and an upper side that is provided as a visible face, where the board is made of weather resistant material and provided for formation of a floor covering (50) in connection with a connection element (20) that is arranged on the upper side. A fixation mold enables fixation of the board with the connection element at the lower side in a form-fit manner for guiding the partial joint-less floor covering, where the connection element is made of plastic material. Another fixation mold stabilizes swiveling position of the board relative to the connection element. An independent claim is also included for a method for manufacturing the floor covering.

IPC 8 full level  
**E01C 5/00** (2006.01); **E01C 5/18** (2006.01); **E01C 5/22** (2006.01); **E01C 13/04** (2006.01)

CPC (source: EP)  
**E01C 5/001** (2013.01); **E01C 5/005** (2013.01); **E01C 5/226** (2013.01); **E01C 13/045** (2013.01)

Citation (search report)  
• [X] WO 2008114124 A1 20080925 - SANTOLIN VALERIA [IT], et al  
• [X] EP 1845194 A1 20071017 - FORNITURE IND B M G [IT]

Cited by  
DE102014107485B4; DE102014107485A1; DE102020111582A1; WO2021219726A1

Designated contracting state (EPC)  
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)  
BA ME

DOCDB simple family (publication)  
**EP 2374932 A2 2011012; EP 2374932 A3 20131218; EP 2374932 B1 20180221**; DE 102010014131 A1 2011013

DOCDB simple family (application)  
**EP 11002925 A 20110407**; DE 102010014131 A 20100407